

HMBT5240

General Purpose Transistors PNP Silicon

Features

- Low collector-emitter saturation voltage
- High current capability
- Improved device reliability due to reduced heat generation
- We declare that the material of product compliance with RoHS requirements.

Applications

- Supply line switching circuits
- Battery management applications
- DC/DC converter applications
- Strobe flash units
- Heavy duty battery powered equipment (motor and lamp drivers)

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-23
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 0.008 gram

Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	Symbol	Value	UNIT
Collector-base voltage	V_{CBO}	-40	V
Collector-emitter voltage	V_{CEO}	-40	V
Emitter-base voltage	V_{EBO}	-5.0	V
Collector current — continuous	I_C	-2.0	A

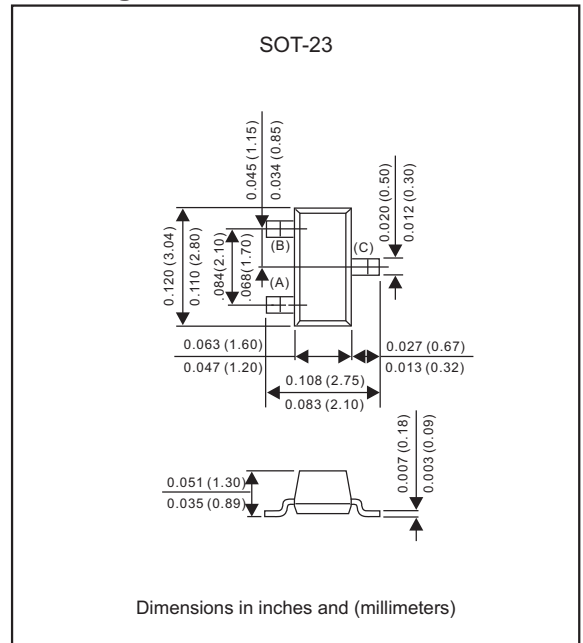
Thermal characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	Symbol	MIN.	TYP.	MAX.	UNIT
Total device dissipation	$T_A = 25^{\circ}\text{C}$ P_D			300	mW
Thermal resistance	Junction to ambient ,note 1 $R_{\theta JA}$			417	$^{\circ}\text{C}/\text{W}$
Thermal resistance	Junction to ambient ,note 2 $R_{\theta JA}$			260	$^{\circ}\text{C}/\text{W}$
Operation junction temperature range	T_J	-55		+150	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55		+150	$^{\circ}\text{C}$

1. Device mounted on a printed-circuit board, single sided copper, tinplated and standard footprint

2. Device mounted on a printed-circuit board, single sided copper, tinplated and mounted pad for collector 1 cm^2

Package outline



HMBT5240

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Collector-base cut-off current	$V_{CB} = -30\text{V}, I_E = 0$	I_{CBO}			-100	nA
Emitter-base cut-off current	$V_{BE} = -4\text{V}, I_C = 0$	I_{EBO}			-100	nA
DC current gain	$I_C = -100\text{mA}, V_{CE} = -2.0\text{V}$	h_{FE}	300			-
	$I_C = -500\text{mA}, V_{CE} = -2.0\text{V}$		260			
	$I_C = -1\text{A}, V_{CE} = -2.0\text{V}$		210			
	$I_C = -2\text{A}, V_{CE} = -2.0\text{V}$		100			
Collector-emitter saturation voltage	$I_C = -100\text{mA}, I_B = -1\text{mA}$	$V_{CE(sat)}$			-100	mV
	$I_C = -500\text{mA}, I_B = -50\text{mA}$				-110	
	$I_C = -750\text{mA}, I_B = -15\text{mA}$				-225	
	$I_C = -1\text{A}, I_B = -50\text{mA}$				-225	
	$I_C = -2\text{A}, I_B = -200\text{mA}$				-350	
Base-emitter saturation voltage	$I_C = -2\text{A}, I_B = -200\text{mA}$	$V_{BE(sat)}$			-1.1	V
Base-emitter turn-on voltage	$V_{CE} = -2\text{V}, I_C = -100\text{mA}$	$V_{BE(on)}$			-0.75	V
Transition frequency	$I_C = -100\text{mA}, V_{CE} = -10\text{V}, f = 100\text{MHz}$	f_T	100			MHz
Collector capacitance	$V_{CB} = -10\text{V}, I_E = I_C = 0, f = 1.0\text{MHz}$	C_C			28	pF

Rating and characteristic curves(HMBT5240)

Fig.1 DC CURRENT GAIN VS.COLLECTOR CURRENT

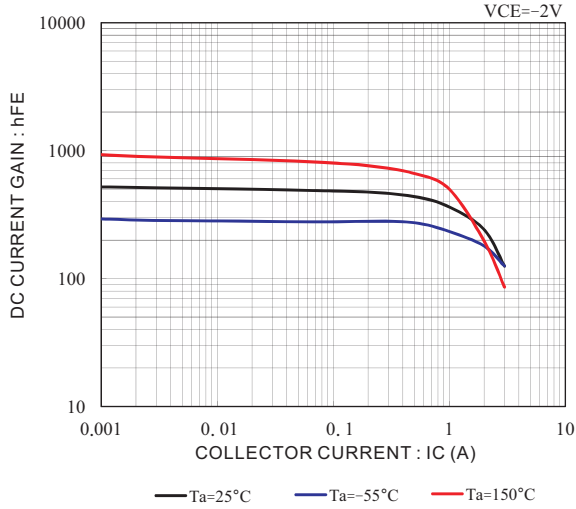


Fig.2 BASE-EMITTER TURN-ON VOLTAGE VS.COLLECTOR CURRENT

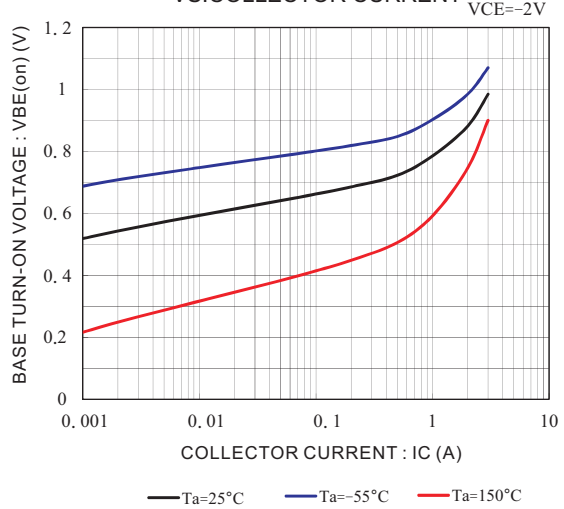


Fig.3 COLLECTOR-EMITTER SATURATION VOLTAGE VS.COLLECTOR CURRENT

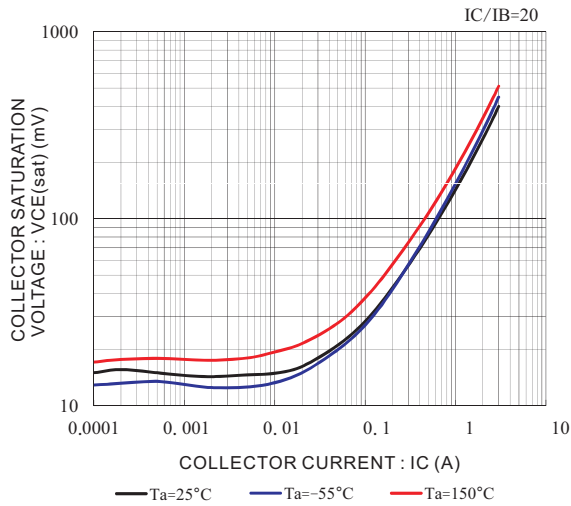


Fig.4 BASE-EMITTER SATURATION VOLTAGE VS.COLLECTOR CURRENT

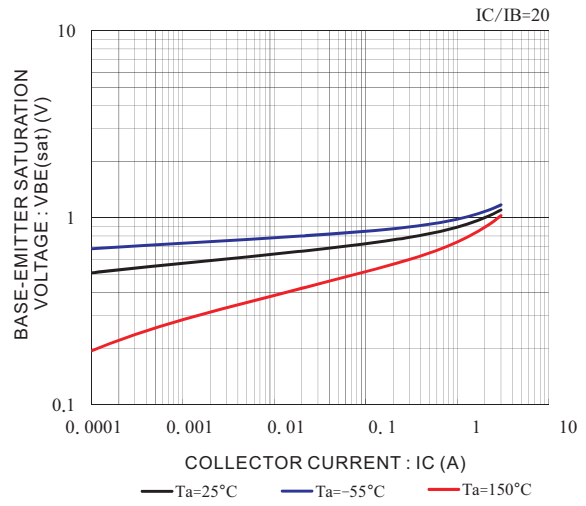


Fig.5 COLLECTOR CURRENT VS.COLLECTOR EMITTER SATURATION VOLTAGE

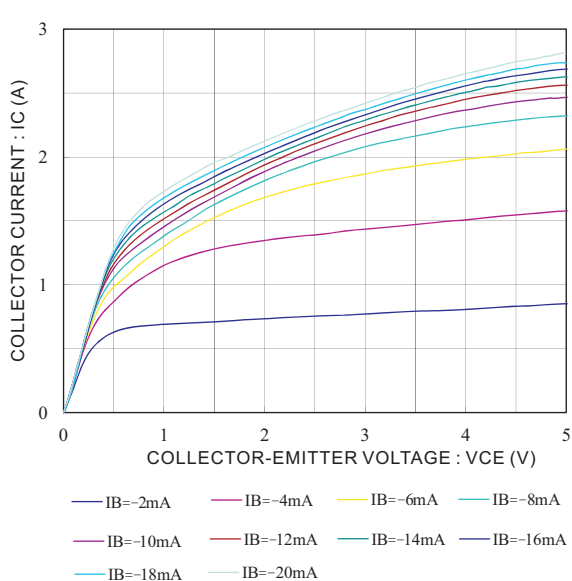
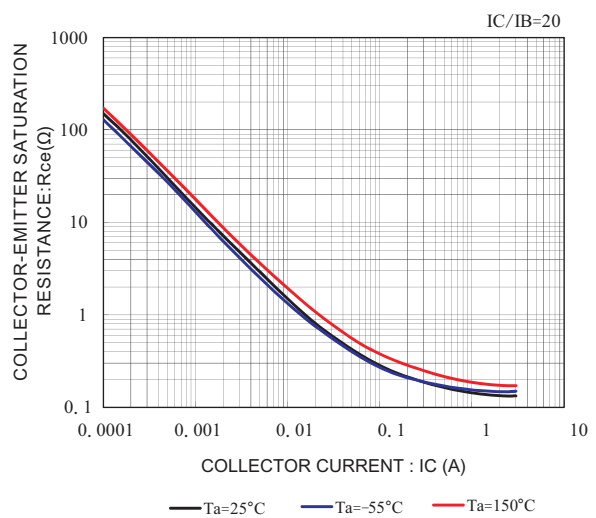
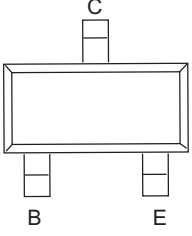
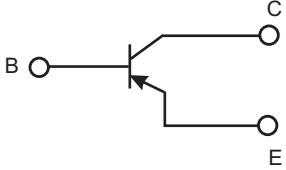


Fig.6 COLLECTOR-EMITTER SATURATION RESISTANCE VS.COLLECTOR CURRENT



HMBT5240

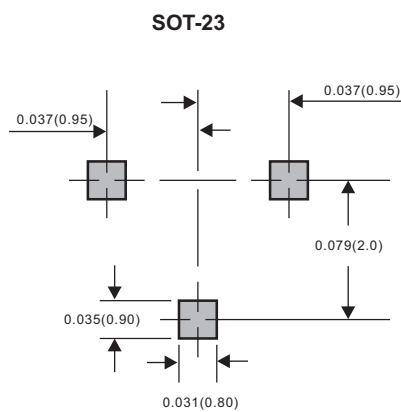
Pinning information

Pin	Simplified outline	Symbol
PinB Base PinC Collector PinE Emitter		

Marking

Type number	Marking code
HMBT5240	ZF

Suggested solder pad layout



Dimensions in inches and (millimeters)